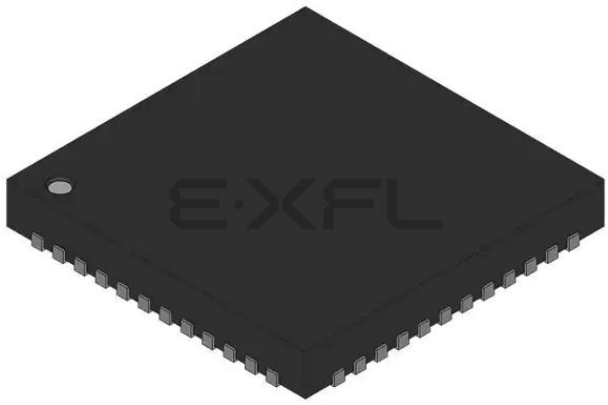

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Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
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Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
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Supplier Device Package	48-QFN-EP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=s9s12gn32f0mft

Table 2-21. Block Register Map (G3) (continued)

Global Address Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x026D PPSJ	R	0	0	0	0	PPSJ3	PPSJ2	PPSJ1	PPSJ0
	W								
0x026E PIEJ	R	0	0	0	0	PIEJ3	PIEJ2	PIEJ1	PIEJ0
	W								
0x026F PIFJ	R	0	0	0	0	PIFJ3	PIFJ2	PIFJ1	PIFJ0
	W								
0x0270 PT0AD	R	0	0	0	0	PT0AD3	PT0AD2	PT0AD1	PT0AD0
	W								
0x0271 PT1AD	R	PT1AD7	PT1AD6	PT1AD5	PT1AD4	PT1AD3	PT1AD2	PT1AD1	PT1AD0
	W								
0x0272 PTI0AD	R	0	0	0	0	PTI0AD3	PTI0AD2	PTI0AD1	PTI0AD0
	W								
0x0273 PTI1AD	R	PTI1AD7	PTI1AD6	PTI1AD5	PTI1AD4	PTI1AD3	PTI1AD2	PTI1AD1	PTI1AD0
	W								
0x0274 DDR0AD	R	0	0	0	0	DDR0AD3	DDR0AD2	DDR0AD1	DDR0AD0
	W								
0x0275 DDR1AD	R	DDR1AD7	DDR1AD6	DDR1AD5	DDR1AD4	DDR1AD3	DDR1AD2	DDR1AD1	DDR1AD0
	W								
0x0276 Reserved	R	0	0	0	0	0	0	0	0
	W								
0x0277 Reserved	R	0	0	0	0	0	0	0	0
	W								
0x0278 PER0AD	R	0	0	0	0	PER0AD3	PER0AD2	PER0AD1	PER0AD0
	W								
0x0279 PER1AD	R	PER1AD7	PER1AD6	PER1AD5	PER1AD4	PER1AD3	PER1AD2	PER1AD1	PER1AD0
	W								
0x027A PPS0AD	R	0	0	0	0	PPS0AD3	PPS0AD2	PPS0AD1	PPS0AD0
	W								
0x027B PPS1AD	R	PPS1AD7	PPS1AD6	PPS1AD5	PPS1AD4	PPS1AD3	PPS1AD2	PPS1AD1	PPS1AD0
	W								

= Unimplemented or Reserved

Table 2-50. IOC2 Routing Options

PRR0T21	PRR0T20	IOC2 Associated Pin
0	0	PS5 - IOC2
0	1	PE0 - IOC2
1	0	PAD4 - IOC2
1	1	Reserved

Table 2-51. SCI0 Routing Options

PRR0S1	PRR0S0	SCI0 Associated Pin
0	0	PE0 - RXD, PE1 - TXD
0	1	PS4 - RXD, PS7 - TXD
1	0	PAD4 - RXD, PAD5 - TXD
1	1	Reserved

2.4.3.27 Port M Data Register (PTM)

Address 0x0250 (G1, G2) Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	0	0	0	0	PTM3	PTM2	PTM1	PTM0
W								
Reset	0	0	0	0	0	0	0	0

Address 0x0250 (G3) Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	PTM1	PTM0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-28. Port M Data Register (PTM)

[1] Read: Anytime. The data source is depending on the data direction value.
Write: Anytime

Table 2-52. PTM Register Field Descriptions

Field	Description
3-0 PTM	**Port M general-purpose input/output data**—Data Register When not used with an alternative signal, the associated pin can be used as general-purpose I/O. In general-purpose output mode the port data register bit value is driven to the pin. If the associated data direction bit is set to 1, a read returns the value of the port data register bit, otherwise the buffered pin input state is read.

[1] Read: Anytime
Write: Anytime, write 1 to clear

Table 2-67. PIFP Register Field Descriptions

Field	Description
7-0 PIFP	**Port P interrupt flag—** This flag asserts after a valid active edge was detected on the related pin (see Section 2.5.4.2, “Pin Interrupts and Wakeup”). This can be a rising or a falling edge based on the state of the polarity select register. An interrupt will occur if the associated interrupt enable bit is set. Writing a logic “1” to the corresponding bit field clears the flag. 1 Active edge on the associated bit has occurred 0 No active edge occurred

Table 3-2. ACMPC Register Field Descriptions (continued)

Field	Description
5 ACICE	ACMP Input Capture Enable— Establishes internal link to a timer input capture channel. When enabled, the associated timer pin is disconnected from the timer input. Refer to ACE description to account for initialization delay on this path. 0 Timer link disabled 1 ACMP output connected to input capture channel 5
4 ACDIEN	ACMP Digital Input Buffer Enable— Enables the input buffers on ACMPP and ACMPM for the pins to be used with digital functions. **Note:** If this bit is set while simultaneously using the pin as an analog port, there is potentially increased power consumption because the digital input buffer may be in the linear region. 0 Input buffers disabled on ACMPP and ACMPM 1 Input buffers enabled on ACMPP and ACMPM
3-2 ACMOD [1:0]	ACMP Mode— Selects the type of compare event setting ACIF. 00 Flag setting disabled 01 Comparator output rising edge 10 Comparator output falling edge 11 Comparator output rising or falling edge
0 ACE	ACMP Enable— This bit enables the ACMP module and takes it into normal mode (see Section 3.5, “Modes of Operation”). This bit also connects the related input pins with the module’s low pass input filters. When the module is not enabled, it remains in low power shutdown mode. **Note:** After setting ACE=1 an initialization delay of 63 bus clock cycles must be accounted for. During this time the comparator output path to all subsequent logic (ACO, ACIF, timer link, excl. ACMPO) is held at its current state. When resetting ACE to 0 the current state of the comparator will be maintained. 0 ACMP disabled 1 ACMP enabled

3.6.2.2 ACMP Status Register (ACMPS)

Address 0x0261 Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	ACIF	ACO	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

Figure 3-4. ACMP Status Register (ACMPS)

[1] Read: Anytime
Write:
ACIF: Anytime, write 1 to clear
ACO: Never

Chapter 5
S12G Memory Map Controller (S12GMMCV1)

Table 5-1. Revision History Table

Rev. No. (Item No.)	Date (Submitted By)	Sections Affected	Substantial Change(s)
01.02	20-May 2010		Updates for S12VR48 and S12VR64

5.1 Introduction

The S12GMMC module controls the access to all internal memories and peripherals for the CPU12 and S12SBDM module. It regulates access priorities and determines the address mapping of the on-chip resources. Figure 5-1 shows a block diagram of the S12GMMC module.

5.1.1 Glossary

Table 5-2. Glossary Of Terms

Term	Definition
Local Addresses	Address within the CPU12's Local Address Map (Figure 5-11)
Global Address	Address within the Global Address Map (Figure 5-11)
Aligned Bus Access	Bus access to an even address.
Misaligned Bus Access	Bus access to an odd address.
NS	Normal Single-Chip Mode
SS	Special Single-Chip Mode
Unimplemented Address Ranges	Address ranges which are not mapped to any on-chip resource.
NVM	Non-volatile Memory; Flash or EEPROM
IFR	NVM Information Row. Refer to FTMRG Block Guide

5.1.2 Overview

The S12GMMC connects the CPU12's and the S12SBDM's bus interfaces to the MCU's on-chip resources (memories and peripherals). It arbitrates the bus accesses and determines all of the MCU's memory maps. Furthermore, the S12GMMC is responsible for constraining memory accesses on secured devices and for selecting the MCU's functional mode.

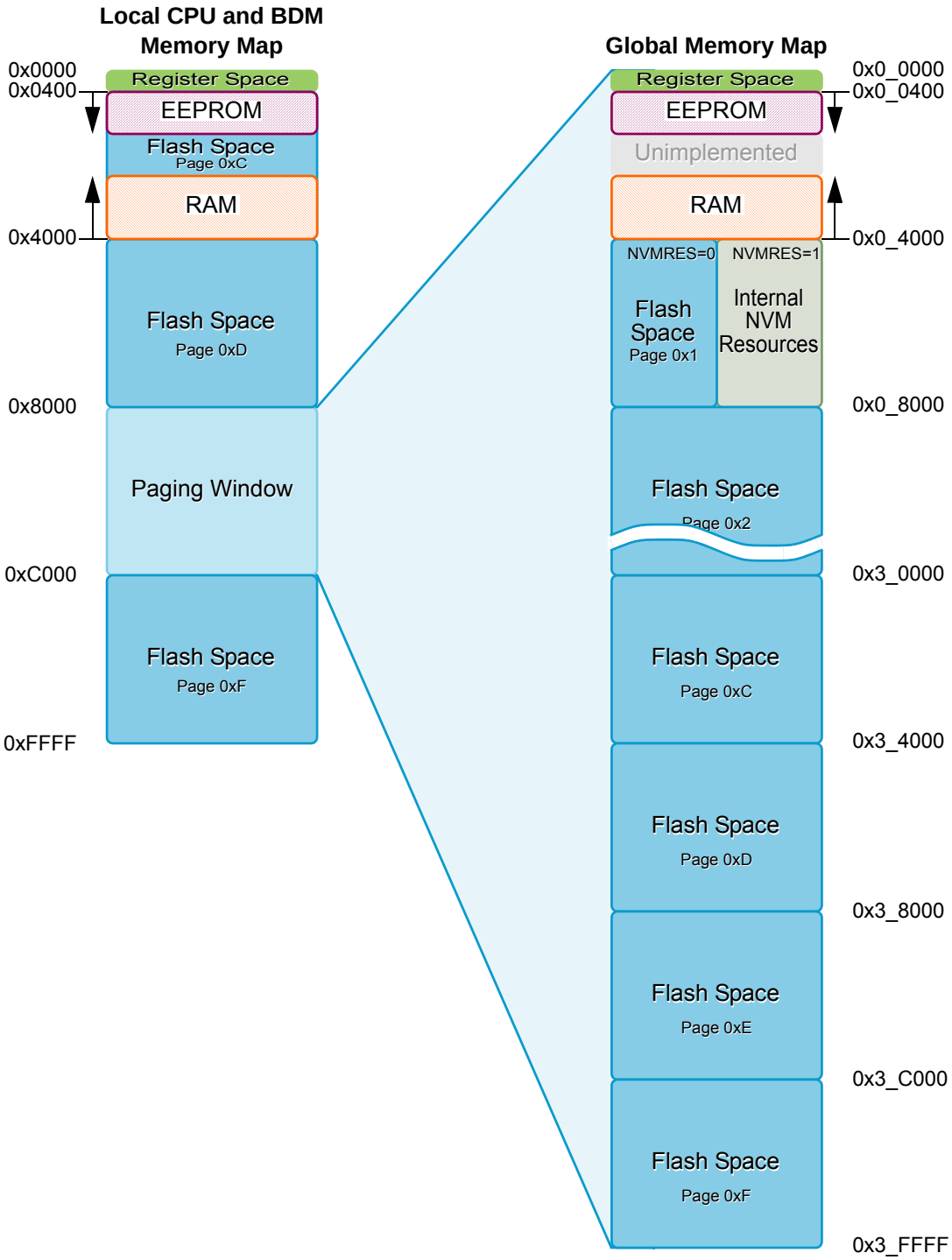

Figure 5-11. Local to Global Address Mapping

Table 6-3. IVBR Field Descriptions

Field	Description
7–0 IVB_ADDR[7:0]	**Interrupt Vector Base Address Bits** — These bits represent the upper byte of all vector addresses. Out of reset these bits are set to 0xFF (that means vectors are located at 0xFF80–0xFFFE) to ensure compatibility to HCS12. **Note:** A system reset will initialize the interrupt vector base register with “0xFF” before it is used to determine the reset vector address. Therefore, changing the IVBR has no effect on the location of the three reset vectors (0xFFFA–0xFFFE). **Note:** If the BDM is active (that means the CPU is in the process of executing BDM firmware code), the contents of IVBR are ignored and the upper byte of the vector address is fixed as “0xFF”. This is done to enable handling of all non-maskable interrupts in the BDM firmware.

6.4 Functional Description

The INT module processes all exception requests to be serviced by the CPU module. These exceptions include interrupt vector requests and reset vector requests. Each of these exception types and their overall priority level is discussed in the subsections below.

6.4.1 S12S Exception Requests

The CPU handles both reset requests and interrupt requests. A priority decoder is used to evaluate the priority of pending interrupt requests.

6.4.2 Interrupt Prioritization

The INT module contains a priority decoder to determine the priority for all interrupt requests pending for the CPU. If more than one interrupt request is pending, the interrupt request with the higher vector address wins the prioritization.

The following conditions must be met for an I bit maskable interrupt request to be processed.

1. The local interrupt enabled bit in the peripheral module must be set.
2. The I bit in the condition code register (CCR) of the CPU must be cleared.
3. There is no SWI, TRAP, or X bit maskable request pending.

NOTE

All non I bit maskable interrupt requests always have higher priority than the I bit maskable interrupt requests. If the X bit in the CCR is cleared, it is possible to interrupt an I bit maskable interrupt by an X bit maskable interrupt. It is possible to nest non maskable interrupt requests, for example by nesting SWI or TRAP calls.

Since an interrupt vector is only supplied at the time when the CPU requests it, it is possible that a higher priority interrupt request could override the original interrupt request that caused the CPU to request the vector. In this case, the CPU will receive the highest priority vector and the system will process this interrupt request first, before the original interrupt request is processed.

16-bit misaligned reads and writes are generally not allowed. If attempted by BDM hardware command, the BDM ignores the least significant bit of the address and assumes an even address from the remaining bits.

For hardware data read commands, the external host must wait at least 150 bus clock cycles after sending the address before attempting to obtain the read data. This is to be certain that valid data is available in the BDM shift register, ready to be shifted out. For hardware write commands, the external host must wait 150 bus clock cycles after sending the data to be written before attempting to send a new command. This is to avoid disturbing the BDM shift register before the write has been completed. The 150 bus clock cycle delay in both cases includes the maximum 128 cycle delay that can be incurred as the BDM waits for a free cycle before stealing a cycle.

For BDM firmware read commands, the external host should wait at least 48 bus clock cycles after sending the command opcode and before attempting to obtain the read data. The 48 cycle wait allows enough time for the requested data to be made available in the BDM shift register, ready to be shifted out.

For BDM firmware write commands, the external host must wait 36 bus clock cycles after sending the data to be written before attempting to send a new command. This is to avoid disturbing the BDM shift register before the write has been completed.

The external host should wait for at least for 76 bus clock cycles after a TRACE1 or GO command before starting any new serial command. This is to allow the CPU to exit gracefully from the standard BDM firmware lookup table and resume execution of the user code. Disturbing the BDM shift register prematurely may adversely affect the exit from the standard BDM firmware lookup table.

NOTE

If the bus rate of the target processor is unknown or could be changing, it is recommended that the ACK (acknowledge function) is used to indicate when an operation is complete. When using ACK, the delay times are automated.

Figure 7-6 represents the BDM command structure. The command blocks illustrate a series of eight bit times starting with a falling edge. The bar across the top of the blocks indicates that the BKGD line idles in the high state. The time for an 8-bit command is 8 × 16 target clock cycles.[1]

1. Target clock cycles are cycles measured using the target MCU's serial clock rate. See Section 7.4.6, "BDM Serial Interface" and Section 7.3.2.1, "BDM Status Register (BDMSTS)" for information on how serial clock rate is selected.

NOTE

Care should be taken to ensure that the bus frequency does not exceed the specified maximum when frequency modulation is enabled.

Table 10-7. CPMUPLL Field Descriptions

Field	Description
5, 4 FM1, FM0	PLL **Frequency Modulation Enable Bits** — FM1 and FM0 enable frequency modulation on the VCOCLK. This is to reduce noise emission. The modulation frequency is f_{ref} divided by 16. See Table 10-8 for coding.

Table 10-8. FM Amplitude selection

FM1	FM0	FM Amplitude / f_{VCO} Variation
0	0	FM off
0	1	±1%
1	0	±2%
1	1	±4%

10.3.2.8 S12CPMU RTI Control Register (CPMURTI)

This register selects the time-out period for the Real Time Interrupt.

The clock source for the RTI is either IRCCLK or OSCCLK depending on the setting of the RTIOSCSEL bit. In Stop Mode with PSTP=1 (Pseudo Stop Mode) and RTIOSCSEL=1 the RTI continues to run, else the RTI counter halts in Stop Mode.

0x003B

	7	6	5	4	3	2	1	0
R W	RTDEC	RTR6	RTR5	RTR4	RTR3	RTR2	RTR1	RTR0
Reset	0	0	0	0	0	0	0	0

Figure 10-11. S12CPMU RTI Control Register (CPMURTI)

Read: Anytime

Write: Anytime

11.3.2.9 ATD Status Register 2 (ATDSTAT2)

This read-only register contains the Conversion Complete Flags CCF[7:0].

Module Base + 0x000A

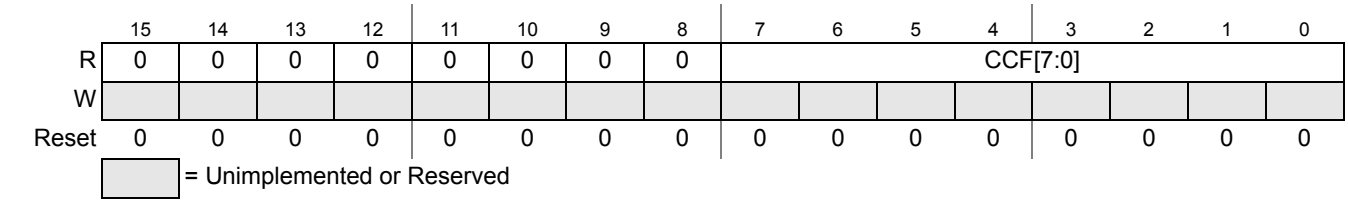

Figure 11-11. ATD Status Register 2 (ATDSTAT2)

Read: Anytime

Write: Anytime (for details see Table 11-18 below)

Table 11-18. ATDSTAT2 Field Descriptions

Field	Description
7–0 CCF[7:0]	**Conversion Complete Flag *n* (*n*= 7, 6, 5, 4, 3, 2, 1, 0) (*n conversion number, NOT channel number!)*—** A conversion complete flag is set at the end of each conversion in a sequence. The flags are associated with the conversion position in a sequence (and also the result register number). Therefore in non-fifo mode, CCF[4] is set when the fifth conversion in a sequence is complete and the result is available in result register ATDDR4; CCF[5] is set when the sixth conversion in a sequence is complete and the result is available in ATDDR5, and so forth. If automatic compare of conversion results is enabled (CMPE[*n*]=1 in ATDCMPE), the conversion complete flag is only set if comparison with ATDDR*n* is true. If ACMPIE=1 a compare interrupt will be requested. In this case, as the ATDDR*n* result register is used to hold the compare value, the result will not be stored there at the end of the conversion but is lost. A flag CCF[*n*] is cleared when one of the following occurs: A) Write to ATDCTL5 (a new conversion sequence is started) B) If AFFC=0, write “1” to CCF[*n*] C) If AFFC=1 and CMPE[*n*]=0, read of result register ATDDR*n* D) If AFFC=1 and CMPE[*n*]=1, write to result register ATDDR*n* In case of a concurrent set and clear on CCF[*n*]: The clearing by method A) will overwrite the set. The clearing by methods B) or C) or D) will be overwritten by the set. 0 Conversion number *n* not completed or successfully compared 1 If (CMPE[*n*]=0): Conversion number *n* has completed. Result is ready in ATDDR*n*. If (CMPE[*n*]=1): Compare for conversion result number *n* with compare value in ATDDR*n*, using compare operator CMPGT[*n*] is true. (No result available in ATDDR*n*)

[1]If only AN0 should be converted use MULT=0.

13.3.2.2 ATD Control Register 1 (ATDCTL1)

Writes to this register will abort current conversion sequence.

Module Base + 0x0001

	7	6	5	4	3	2	1	0
R W	ETRIGSEL	SRES1	SRES0	SMP_DIS	ETRIGCH3	ETRIGCH2	ETRIGCH1	ETRIGCH0
Reset	0	0	1	0	1	1	1	1

Figure 13-4. ATD Control Register 1 (ATDCTL1)

Read: Anytime

Write: Anytime

Table 13-3. ATDCTL1 Field Descriptions

Field	Description
7 ETRIGSEL	**External Trigger Source Select** — This bit selects the external trigger source to be either one of the AD channels or one of the ETRIG3-0 inputs. See device specification for availability and connectivity of ETRIG3-0 inputs. If a particular ETRIG3-0 input option is not available, writing a 1 to ETRISEL only sets the bit but has no effect, this means that one of the AD channels (selected by ETRIGCH3-0) is configured as the source for external trigger. The coding is summarized in Table 13-5.
6–5 SRES[1:0]	**A/D Resolution Select** — These bits select the resolution of A/D conversion results. See Table 13-4 for coding.
4 SMP_DIS	**Discharge Before Sampling Bit** 0 No discharge before sampling. 1 The internal sample capacitor is discharged before sampling the channel. This adds 2 ATD clock cycles to the sampling time. This can help to detect an open circuit instead of measuring the previous sampled channel.
3–0 ETRIGCH[3:0]	**External Trigger Channel Select** — These bits select one of the AD channels or one of the ETRIG3-0 inputs as source for the external trigger. The coding is summarized in Table 13-5.

Table 13-4. A/D Resolution Coding

SRES1	SRES0	A/D Resolution
0	0	8-bit data
0	1	10-bit data
1	0	Reserved
1	1	Reserved

16.1.3 Block Diagram

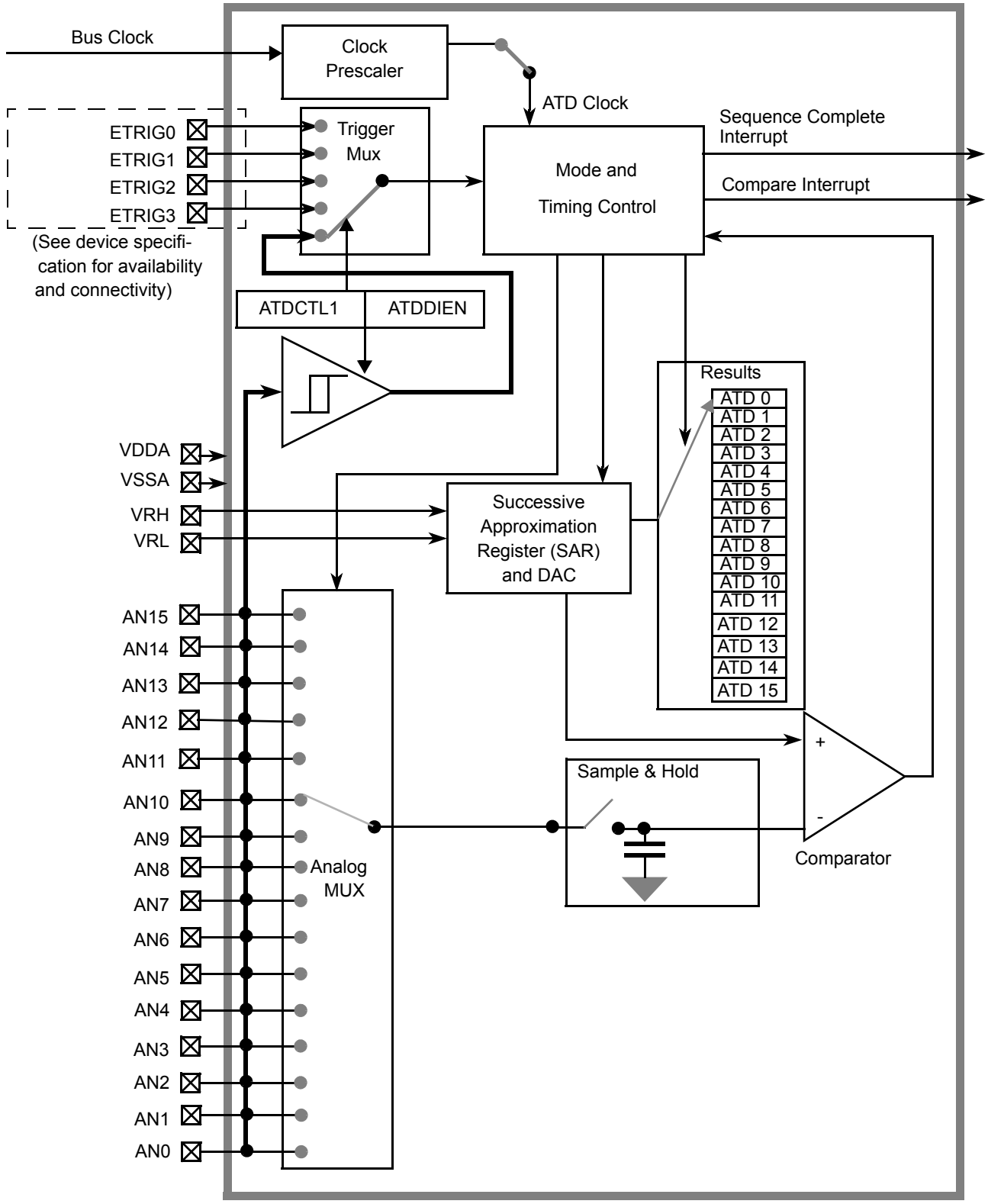

Figure 16-1. ADC12B16C Block Diagram

18.3.2.15 MSCAN Receive Error Counter (CANRXERR)

This register reflects the status of the MSCAN receive error counter.

Module Base + 0x000E — Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0
W								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 18-18. MSCAN Receive Error Counter (CANRXERR)

[1] Read: Only when in sleep mode (SLPRQ = 1 and SLPAK = 1) or initialization mode (INITRQ = 1 and INITAK = 1)
Write: Unimplemented

NOTE

Reading this register when in any other mode other than sleep or initialization mode may return an incorrect value. For MCUs with dual CPUs, this may result in a CPU fault condition.

18.3.2.16 MSCAN Transmit Error Counter (CANTXERR)

This register reflects the status of the MSCAN transmit error counter.

Module Base + 0x000F — Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0
W								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 18-19. MSCAN Transmit Error Counter (CANTXERR)

[1] Read: Only when in sleep mode (SLPRQ = 1 and SLPAK = 1) or initialization mode (INITRQ = 1 and INITAK = 1)
Write: Unimplemented

NOTE

Reading this register when in any other mode other than sleep or initialization mode, may return an incorrect value. For MCUs with dual CPUs, this may result in a CPU fault condition.

23.3.2 Register Descriptions

This section consists of register descriptions in address order. Each description includes a standard register diagram with an associated figure number. Details of register bit and field function follow the register diagrams, in bit order.

Only bits related to implemented channels are valid.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0000 TIOS	R	IOS7	IOS6	IOS5	IOS4	IOS3	IOS2	IOS1	IOS0
	W								
0x0001 CFORC	R	0	0	0	0	0	0	0	0
	W	FOC7	FOC6	FOC5	FOC4	FOC3	FOC2	FOC1	FOC0
0x0002 OC7M	R	OC7M7	OC7M6	OC7M5	OC7M4	OC7M3	OC7M2	OC7M1	OC7M0
	W								
0x0003 OC7D	R	OC7D7	OC7D6	OC7D5	OC7D4	OC7D3	OC7D2	OC7D1	OC7D0
	W								
0x0004 TCNTH	R	TCNT15	TCNT14	TCNT13	TCNT12	TCNT11	TCNT10	TCNT9	TCNT8
	W								
0x0005 TCNTL	R	TCNT7	TCNT6	TCNT5	TCNT4	TCNT3	TCNT2	TCNT1	TCNT0
	W								
0x0006 TSCR1	R	TEN	TSWAI	TSFRZ	TFFCA	PRNT	0	0	0
	W								
0x0007 TTOV	R	TOV7	TOV6	TOV5	TOV4	TOV3	TOV2	TOV1	TOV0
	W								
0x0008 TCTL1	R	OM7	OL7	OM6	OL6	OM5	OL5	OM4	OL4
	W								
0x0009 TCTL2	R	OM3	OL3	OM2	OL2	OM1	OL1	OM0	OL0
	W								
0x000A TCTL3	R	EDG7B	EDG7A	EDG6B	EDG6A	EDG5B	EDG5A	EDG4B	EDG4A
	W								
0x000B TCTL4	R	EDG3B	EDG3A	EDG2B	EDG2A	EDG1B	EDG1A	EDG0B	EDG0A
	W								
0x000C TIE	R	C7I	C6I	C5I	C4I	C3I	C2I	C1I	C0I
	W								
0x000D TSCR2	R	TOI	0	0	0	TCRE	PR2	PR1	PR0
	W								
0x000E TFLG1	R	C7F	C6F	C5F	C4F	C3F	C2F	C1F	C0F
	W								
0x000F TFLG2	R	TOF	0	0	0	0	0	0	0
	W								
0x0010–0x001F TCxH–TCxL[1]	R	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
	W								
	R	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	W								
0x0020 PACTL	R	0	PAEN	PAMOD	PEDGE	CLK1	CLK0	PAOVI	PAI
	W								

Figure 23-5. TIM16B8CV3 Register Summary (Sheet 1 of 2)

25.4.6.2 Erase Verify Block Command

The Erase Verify Block command allows the user to verify that an entire P-Flash or EEPROM block has been erased. The FCCOB FlashBlockSelectionCode[1:0] bits determine which block must be verified.

Table 25-33. Erase Verify Block Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters	
000	0x02	Flash block selection code [1:0]. See Table 25-34

Table 25-34. Flash block selection code description

Selection code[1:0]	Flash block to be verified
00	EEPROM
01	Invalid (ACCERR)
10	Invalid (ACCERR)
11	P-Flash

Upon clearing CCIF to launch the Erase Verify Block command, the Memory Controller will verify that the selected P-Flash or EEPROM block is erased. The CCIF flag will set after the Erase Verify Block operation has completed.If the block is not erased, it means blank check failed, both MGSTAT bits will be set.

Table 25-35. Erase Verify Block Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 000 at command launch
		Set if an invalid FlashBlockSelectionCode[1:0] is supplied
	FPVIOL	None
	MGSTAT1	Set if any errors have been encountered during the read or if blank check failed.
	MGSTAT0	Set if any non-correctable errors have been encountered during the read or if blank check failed.

25.4.6.3 Erase Verify P-Flash Section Command

The Erase Verify P-Flash Section command will verify that a section of code in the P-Flash memory is erased. The Erase Verify P-Flash Section command defines the starting point of the code to be verified and the number of phrases.

Chapter 27
64 KByte Flash Module (S12FTMRG64K1V1)

Table 27-1. Revision History

Revision Number	Revision Date	Sections Affected	Description of Changes
V01.04	17 Jun 2010	27.4.6.1/27-950 27.4.6.2/27-951 27.4.6.3/27-951 27.4.6.14/27-961	Clarify Erase Verify Commands Descriptions related to the bits MGSTAT[1:0] of the register FSTAT.
V01.05	20 aug 2010	27.4.6.2/27-951 27.4.6.12/27-958 27.4.6.13/27-960	Updated description of the commands RD1BLK, MLOADU and MLOADF
Rev.1.27	31 Jan 2011	27.3.2.9/27-933	Updated description of protection on Section 27.3.2.9

27.1 Introduction

The FTMRG64K1 module implements the following:

- 64Kbytes of P-Flash (Program Flash) memory
- 2 Kbytes of EEPROM memory

The Flash memory is ideal for single-supply applications allowing for field reprogramming without requiring external high voltage sources for program or erase operations. The Flash module includes a memory controller that executes commands to modify Flash memory contents. The user interface to the memory controller consists of the indexed Flash Common Command Object (FCCOB) register which is written to with the command, global address, data, and any required command parameters. The memory controller must complete the execution of a command before the FCCOB register can be written to with a new command.

CAUTION

A Flash word or phrase must be in the erased state before being programmed. Cumulative programming of bits within a Flash word or phrase is not allowed.

The Flash memory may be read as bytes and aligned words. Read access time is one bus cycle for bytes and aligned words. For misaligned words access, the CPU has to perform twice the byte read access command. For Flash memory, an erased bit reads 1 and a programmed bit reads 0.

CAUTION

The FCLKDIV register should never be written while a Flash command is executing (CCIF=0).

Table 27-7. FCLKDIV Field Descriptions

Field	Description
7 FDIVLD	Clock Divider Loaded 0 FCLKDIV register has not been written since the last reset 1 FCLKDIV register has been written since the last reset
6 FDIVLCK	Clock Divider Locked 0 FDIV field is open for writing 1 FDIV value is locked and cannot be changed. Once the lock bit is set high, only reset can clear this bit and restore writability to the FDIV field in normal mode.
5–0 FDIV[5:0]	**Clock Divider Bits** — FDIV[5:0] must be set to effectively divide BUSCLK down to 1 MHz to control timed events during Flash program and erase algorithms. Table 27-8 shows recommended values for FDIV[5:0] based on the BUSCLK frequency. Please refer to Section 27.4.4, “Flash Command Operations,” for more information.

Table 27-8. FDIV values for various BUSCLK Frequencies

BUSCLK Frequency (MHz)		FDIV[5:0]	BUSCLK Frequency (MHz)		FDIV[5:0]
MIN[1]	MAX[2]		MIN[1]	MAX[2]	
1.0	1.6	0x00	16.6	17.6	0x10
1.6	2.6	0x01	17.6	18.6	0x11
2.6	3.6	0x02	18.6	19.6	0x12
3.6	4.6	0x03	19.6	20.6	0x13
4.6	5.6	0x04	20.6	21.6	0x14
5.6	6.6	0x05	21.6	22.6	0x15
6.6	7.6	0x06	22.6	23.6	0x16
7.6	8.6	0x07	23.6	24.6	0x17
8.6	9.6	0x08	24.6	25.6	0x18
9.6	10.6	0x09			
10.6	11.6	0x0A			
11.6	12.6	0x0B			
12.6	13.6	0x0C			
13.6	14.6	0x0D			
14.6	15.6	0x0E			
15.6	16.6	0x0F			

1 BUSCLK is Greater Than this value.

2 BUSCLK is Less Than or Equal to this value.

The Flash memory may be read as bytes and aligned words. Read access time is one bus cycle for bytes and aligned words. For misaligned words access, the CPU has to perform twice the byte read access command. For Flash memory, an erased bit reads 1 and a programmed bit reads 0.

It is possible to read from P-Flash memory while some commands are executing on EEPROM memory. It is not possible to read from EEPROM memory while a command is executing on P-Flash memory. Simultaneous P-Flash and EEPROM operations are discussed in Section 30.4.5.

Both P-Flash and EEPROM memories are implemented with Error Correction Codes (ECC) that can resolve single bit faults and detect double bit faults. For P-Flash memory, the ECC implementation requires that programming be done on an aligned 8 byte basis (a Flash phrase). Since P-Flash memory is always read by half-phrase, only one single bit fault in an aligned 4 byte half-phrase containing the byte or word accessed will be corrected.

30.1.1 Glossary

Command Write Sequence — An MCU instruction sequence to execute built-in algorithms (including program and erase) on the Flash memory.

EEPROM Memory — The EEPROM memory constitutes the nonvolatile memory store for data.

EEPROM Sector — The EEPROM sector is the smallest portion of the EEPROM memory that can be erased. The EEPROM sector consists of 4 bytes.

NVM Command Mode — An NVM mode using the CPU to setup the FCCOB register to pass parameters required for Flash command execution.

Phrase — An aligned group of four 16-bit words within the P-Flash memory. Each phrase includes two sets of aligned double words with each set including 7 ECC bits for single bit fault correction and double bit fault detection within each double word.

P-Flash Memory — The P-Flash memory constitutes the main nonvolatile memory store for applications.

P-Flash Sector — The P-Flash sector is the smallest portion of the P-Flash memory that can be erased. Each P-Flash sector contains 512 bytes.

Program IFR — Nonvolatile information register located in the P-Flash block that contains the Version ID, and the Program Once field.

30.1.2 Features

30.1.2.1 P-Flash Features

- 192 Kbytes of P-Flash memory divided into 384 sectors of 512 bytes

All VDDX pins are internally connected by metal.

All VSSX pins are internally connected by metal.

VDDA, VDDX and VSSA, VSSX are connected by diodes for ESD protection.

NOTE

In the following context V_{DD35} is used for either VDDA, VDDR, and VDDX; V_{SS35} is used for either VSSA and VSSX unless otherwise noted.

I_{DD35} denotes the sum of the currents flowing into the VDDA, VDDX and VDDR pins.

A.1.3 Pins

There are four groups of functional pins.

A.1.3.1 I/O Pins

The I/O pins have a level in the range of 3.13V to 5.5V. This class of pins is comprised of all port I/O pins, the analog inputs, BKGD and the $\overline{\text{RESET}}$ pins. Some functionality may be disabled.

A.1.3.2 Analog Reference

This group consists of the VRH pin.

A.1.3.3 Oscillator

The pins EXTAL, XTAL dedicated to the oscillator have a nominal 1.8V level.

A.1.3.4 TEST

This pin is used for production testing only. The TEST pin must be tied to ground in all applications.

A.1.4 Current Injection

Power supply must maintain regulation within operating V_{DD35} or V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current ($V_{in} > V_{DD35}$) is greater than I_{DD35}, the injection current may flow out of V_{DD35} and could result in external power supply going out of regulation. Ensure external V_{DD35} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power; e.g., if no system clock is present, or if clock rate is very low which would reduce overall power consumption.

A.1.5 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only. A functional operation under or outside those maxima is not guaranteed. Stress beyond those limits may affect the reliability or cause permanent damage of the device.

Table A-22. ADC Conversion Performance 5V range (Junction Temperature From +150°C To +160°C)

S12GNA16, S12GNA32								
Supply voltage 4.5V < V_{DDA} < 5.5 V, +150°C < T_J < 160°C, V_{REF} = V_{RH} - V_{RL} = V_{DDA}, f_{ADCCLK} = 8.0MHz The values are tested to be valid with no port AD output drivers switching simultaneous with conversions.								
Num	**C**	**Rating**[1]		**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	M	Resolution	12-Bit	LSB		1.25		mV
2	M	Differential Nonlinearity	12-Bit	DNL		±2		counts
3	M	Integral Nonlinearity	12-Bit	INL		±2.5		counts
4	M	Absolute Error[2]	12-Bit	AE		±4		counts
5	C	Resolution	10-Bit	LSB		5		mV
6	C	Differential Nonlinearity	10-Bit	DNL		±0.5		counts
7	C	Integral Nonlinearity	10-Bit	INL		±1		counts
8	C	Absolute Error[2]	10-Bit	AE		±2		counts
9	C	Resolution	8-Bit	LSB		20		mV
10	C	Differential Nonlinearity	8-Bit	DNL		±0.3		counts
11	C	Integral Nonlinearity	8-Bit	INL		±0.5		counts
12	C	Absolute Error[2]	8-Bit	AE		±1		counts

1 The 8-bit and 10-bit mode operation is structurally tested in production test. Absolute values are tested in 12-bit mode.

2 These values include the quantization error which is inherently 1/2 count for any A/D converter.